AMENDMENTS TO THE CLAIMS:

This listing of claims replaces all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) An electronic component comprising ~~containing~~:

[[-]] a multi-layer substrate having an upper side and under side, the multi-layer substrate comprising at least one integrated impedance converter; and ~~(MS),~~

[[-]] at least one chip component ~~(CB) having~~ comprising external contacts ~~(AE)~~, ~~wherein~~ the at least one chip component ~~(CB) is~~ being disposed on the upper side of the multi-layer substrate, ~~(MS), characterized in that at least one integrated impedance converter (IW) is disposed in the multi-layer substrate (MS), wherein~~ the at least one chip component ~~(CB) is~~ being electrically connected ~~with~~ to the at least one integrated impedance converter ~~(IW)~~.

2. (Currently Amended) The electronic component ~~according to~~ of claim 1, wherein ~~in which~~ the external contacts ~~(AE) of the at least one chip component (CB) constitute SMD~~ comprise surface mounted device contacts.

3. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~or 2~~, ~~in which~~ wherein the multi-layer substrate ~~(MS)~~ comprises~~, in addition to the impedance~~

~~converter,~~ at least one ~~additional integrated~~ passive circuit element or at least one active circuit element.

4. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 3, in which~~ wherein the at least one chip component ~~(CB)~~ comprises at least one filter circuit.

5. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 4, in which~~ wherein the at least one chip component ~~(CB)~~ comprises at least one resonator ~~operating~~ that operates with surface acoustic waves.

6. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 5, in which~~ wherein the at least one chip component ~~(CB)~~ comprises a resonator ~~operating~~ that operates with bulk acoustic waves.

7. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 6, in which~~ wherein the at least one chip component ~~(CB) is~~ comprises a microwave ceramic filter.

8. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 7, in which~~ wherein the at least one chip component ~~(CB) is~~ comprises an ~~LC~~ inductive-capacitive (LC) chip filter.

9. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 8~~, ~~in which~~ wherein the at least one chip component ~~(CB) is~~ comprises a stripline filter.

10. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 9~~, ~~in which~~ further comprising:

at least one discrete circuit element ~~passive or active circuit element (SE) is~~ disposed on the upper side of the multi-layer substrate, the at least one discrete circuit element comprising an active circuit element or a passive circuit element ~~(MS)~~.

11. (Currently Amended) The electronic component ~~according to~~ of claim 10 ~~at least one of claims 1 to 10~~, wherein ~~in which~~ the at least one discrete circuit element ~~(SE) disposed on the surface of the multi-layer substrate forms~~ comprises at least a part of one of the following: a high-frequency circuit, an adjustment circuit, an impedance converter, an antenna circuit, a diode circuit, a high-pass filter, a low-pass filter, a band-pass filter, a band elimination filter, a power amplifier, a diplexer, a duplexer, a coupler, a directional coupler, a memory element, a balun, and ~~or~~ a mixer.

12. (Currently Amended) The electronic component ~~according to~~ of claim 10 ~~at least one of claims 1 to 11~~, ~~in which~~ wherein the at least one discrete circuit element ~~(SE)~~

~~disposed on the surface of the multi-layer substrate forms~~ comprises at least a part of a high-frequency circuit, a duplexer or a diplexer[[,]]; and

wherein ~~said~~ the at least one discrete circuit element ~~connects~~ assists in connecting the at least one chip component ~~(CB) with~~ to an antenna.

13. (Currently Amended) The electronic component ~~according to~~ of claim 1, further comprising:

at least one circuit element integrated in the multi-layer substrate;

~~at least one of claims 1 to 12~~, ~~in which~~ wherein the at least one circuit element ~~integrated in the multi-layer substrate (MS) forms~~ comprises at least a part of one of the following: a high-~~frequent~~ frequency circuit, an adjustment circuit, an antenna circuit, a diode circuit, a high-pass filter, a low-pass filter, a band-pass filter, a band elimination filter, a power amplifier, a diplexer, a duplexer, a coupler, a directional coupler, a memory element, a balun, and ~~or~~ a mixer.

14. (Currently Amended) The electronic component ~~according to~~ of claim 13, ~~in which~~ wherein at least a part of an adjustment circuit integrated in the multi-layer substrate is formed as one or more strip conductors on the upper side of the multi-layer substrate ~~for later fine tuning~~.

15. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 14~~, ~~in which~~ wherein the multi-layer substrate ~~(MS)~~ comprises a plurality of adjustment circuits.

16. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 15~~, ~~in which~~ wherein the multi-layer substrate comprises ~~(MS) contains~~ ceramic layers.

17. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 16~~, ~~in which~~ wherein the multi-layer substrate ~~(MS) contains~~ comprises layers of silicone or silicone oxide.

18. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 17~~, wherein ~~in which~~ the multi-layer substrate ~~(MS) contains~~ comprises one or more layers of an organic material~~, such as plastic or laminate~~.

19. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 18~~, ~~in which~~ wherein the at least one chip component comprises one or more inputs and outputs; and

wherein at least one input and/or at least one output of the at least one chip component ~~(CB) is used to conduct~~ conducts an asymmetrical signal.

20. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 19~~, wherein the at least one chip component comprises one or more inputs and outputs; and

~~in which the~~ wherein at least one input and/or the at least one output of the at least one chip component ~~(CB) is used to conduct~~ conducts a symmetrical signal.

21. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 20~~, ~~in which the connections~~ wherein the at least one chip component comprises a connection to ground, the connection to ground being made via ~~of the at least one chip component (CB) are connected with~~ an adjustment circuit that is at least partially integrated in the multi-layer substrate; and ~~against the reference ground of the overall component,~~

wherein ~~said~~ the adjustment circuit comprises at least one of ~~element selected from among~~ a coil, a capacitor ~~or~~ and a conductor ~~line segment~~.

22. (Currently Amended) The electronic component ~~according to~~ of claim 10 ~~at least one of claims 1 to 21~~, ~~in which both~~ wherein the at least one chip component ~~(CB)~~ and the at least one discrete circuit element comprise ~~(SE) disposed on the upper side of the multi-layer substrate (MS) constitute SMD elements (~~surface mounted design elements~~)~~.

23. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 22~~, ~~in which~~ wherein the at least one chip component ~~(CB)~~ comprises a housing comprising the ~~(GE)~~ ~~having~~ external contacts ~~(AE)~~.

24. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 23~~, ~~in which~~ wherein the at least one chip component (CB) is connected ~~with~~ to the multi-layer substrate via ~~(MS) by means of~~ wire bonding.

25. (Currently Amended) The electronic component ~~according to~~ of claim 1 ~~at least one of claims 1 to 23~~, ~~in which~~ wherein the at least one chip component ~~(CB)~~ is connected ~~with~~ to the multi-layer substrate via ~~(MS) by means of~~ flip-chip technology.

26. (Currently Amended) ~~Method for the production of the component according to at least one of claims 23 to 25,~~ A method of producing an electronic component comprised of (i) a multi-layer substrate having an upper side and under side, the multi-layer substrate comprising at least one integrated impedance converter, and (ii) at least one chip component comprising external contacts, the method comprising ~~the following steps~~:

[[-]] ~~installation of a~~ installing the at least one chip component in ~~into~~ a housing; and ~~(GE),~~

[[-]] mounting ~~of~~ the housing onto ~~a~~ the upper side of the multi-layer substrate so as to electrically connect the at least one chip component to the integrated impedance converter ~~(MS)~~.

27. (Currently Amended) The method ~~according to~~ of claim 26, ~~wherein the~~ further comprising:

mounting at least one discrete circuit element ~~(SE) is mounted~~ on the upper side of the multi-layer substrate ~~(MS)~~.

28. (Currently Amended) The method ~~according to~~ of claim 27, wherein the at least one chip component ~~(CB)~~ and the at least one discrete circuit element ~~(SE)~~ are attached to the upper side of the multi-layer substrate using a same attaching mechanism ~~(MS) in the same fashion~~.

29. (Currently Amended) The method of claim 27 ~~according to at least one of claims 26 to 28~~, wherein the at least one chip component ~~(CB) disposed on the upper side of the multi-layer substrate~~ and/or the at least one discrete circuit element ~~(SE)~~ is mechanically stabilized ~~with~~ using a casting compound.